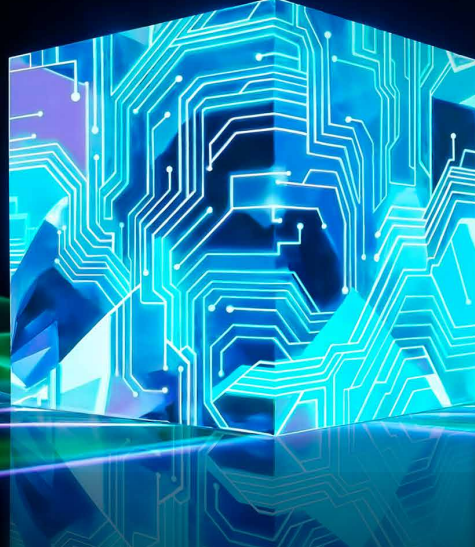


SEMICONDUCTOR INNOVATION AND
INTELLIGENT APPLICATION SUMMIT

SIIAS



2 DEC
2025
TUESDAY

🕒 09:30 - 17:10
📍 Grand Hall, 1/F, 12W, HKSTP, Sha Tin, Hong Kong
🗣️ Language: English

★ Explore interactive **EXPERIENCE ZONES** in the foyer throughout the day, showcasing semiconductor technology with exciting activities and hands-on demonstrations!

PROGRAM RUNDOWN

Time	Programme	Venue
08:45-09:30	Registration and Guest Arrival	
09:30-09:35	Welcome Remarks Prof Tim CHENG Vice-President for Research and Development, HKUST	Hall A & B, Grand Hall
09:35-09:40	Welcome Remarks Mr Lung CHU Corporate Vice President, SEMI	
09:40-09:45	Opening Remarks by Guest of Honor Prof SUN Dong, JP Secretary for Innovation, Technology and Industry, The HKSAR Government	
09:45-09:55	On-stage Group Photo	
09:55-10:15	Use of AI/ML in EDA and Simulation Tools for Semiconductor Design Dr Prith BANERJEE Senior Vice President, Simulation & Analysis Incubation Group, Synopsys	
10:15-10:35	Accelerating the AI Era with Advanced Packaging Mr Choon Khoon LIM Senior Vice President and Chief Counsel for Advanced Packaging, Semiconductor Solutions Segment, ASMPAT	
10:35-10:55	Beyond Moore, Beyond Manual: The New Frontier of AI-Driven 3DIC Design Dr Michael JACKSON Corporate Vice President and General Manager of the System Design and Analysis Group, Cadence	
10:55-11:15	Opportunities and Developments in Semiconductor Ecosystem in Saudi Arabia and Wider MENAT Region Dr Naveed SHERWANI Chairman, National Semi-Conductor Hub, Saudi Arabia	
11:15-12:15	Panel Discussion: The Golden Age of Semiconductor: Driving Innovation, Demand, Talent Development and Collaboration Moderator: Prof Tim CHENG Vice-President for Research and Development, HKUST Panellists: <ul style="list-style-type: none">Dr Prith BANERJEE Senior Vice President, Simulation & Analysis Incubation Group, SynopsysDr GAO Teng CEO, The Hong Kong Microelectronics Research and Development Institute (MRDI)Ms Rosemary HO Chairman and CEO, CIP United Co.Dr Michael JACKSON Corporate Vice President and General Manager of the System Design and Analysis Group, CadenceMr Choon Khoon LIM Senior Vice President and Chief Counsel for Advanced Packaging, Semiconductor Solutions Segment, ASMPATDr Naveed SHERWANI Chairman, National Semi-Conductor Hub, Saudi Arabia	
12:15-14:15	Lunch Break	
14:15-14:35 (Mandarin Session)	Have We Reached the Limits of AI Computing? Mr Steve CHU CEO, Chairman and Founder, NPCTEK	Hall A, Grand Hall
14:35-14:55	Pursuing SoP (System on Panel) for Easier Implementation of HDI (Human Display Interaction) Dr Young LIN Chairman and CEO, FitiPower	
14:55-15:15	AI+IC Technologies for Smart mmWave Sensing in the Era of AIoT Prof Hongtao XU Co-Founder, ICLEGEND MICRO	
15:15-15:35	Coffee Break	
15:35-15:55	The ACCESS Experience: Building a Hub for Global Research, Innovation and Collaboration in AI Chip Design Prof Chi Ying TSUI Professor, HKUST; Associate Center Director, AI Chip Center for Emerging Smart Systems(ACCESS)	
15:55-16:15	AI Arm China: Together! Empower the Next Generation of AI New Era! Mr CHEN Feng CEO, ARM China	
16:15-16:35	WE AI Power Delivery Solutions Mr Alexander GERFER CTO, Würth Elektronik eiSos Group	
16:35-17:05	Panel Discussion: Driving Innovation through Industry-Academic Collaboration: Strategic Insights to Build a Thriving Semiconductor Ecosystem Moderator: Mr Andy WONG Head of Innovation & Technology and Life & Health Sciences, InvestHK Panellists: <ul style="list-style-type: none">Mr CHEN Feng CEO, ARM ChinaMr Alexander GERFER CTO, Würth Elektronik eiSos GroupProf Chi Ying TSUI Professor, HKUST; Associate Center Director, AI Chip Center for Emerging Smart Systems (ACCESS)	
17:05	End of Event	



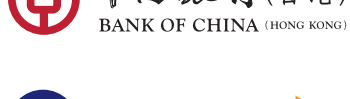
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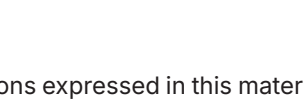
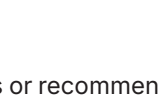
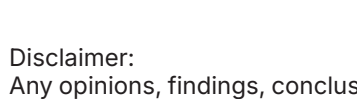
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